

SENSOR IC PACKAGE PORTFOLIO

SENSOR INTEGRATED CIRCUITS

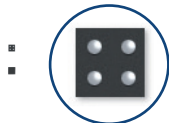
The development of Allegro sensor ICs not only includes leading edge innovations in the area of integrated circuit design but also includes application specific innovation in the area of custom package design.

A small sampling of Allegro's custom packaging developments include:

- Proprietary, integrated magnet packages that simplify magnetic system design in automotive speed sensing applications. See the SE, SG, SH and SJ packages.
- Revolutionary, integrated current sensing packages with high bandwidth magnetic design features. See the SOIC, QSOP, EX, and CA/CB packages with integrated, low resistance current conductors and the 1 mm thick KT package.
- Small footprint, low profile DFN packages for communications and consumer products. See the EW and CG packages.

Low Profile, Smallest Footprint Packages

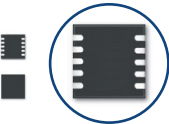
CG (WLCSP)
Terminals: 4
Size: .96 x .96 mm body width



EW (DFN)
Terminals: 6
Size: 1.5 x 2 mm body width



EJ (TDFN)
Terminals: 3-16
Size: 3 x 3 mm body width



Surface Mount Packages

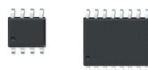
LH (SOT23W)
Terminals: 3



LC (SOIC-8)
Terminals: 8



L (SOIC-8 and SOIC-16)
Terminals: 8, 16



LE (TSSOP)
Terminals: 8, 14, 24



Single In-Line Packages

UA (TO-92)
Terminals: 3



K
Terminals: 4



KT
Terminals: 4



KN
Terminals: 4



UC
Terminals: 3



Integrated Magnet Packages

SE
Terminals: 4



SG
Terminals: 4



SH
Terminals: 4



SJ
Terminals: 4



SP
Terminals: 3



Current Sensing Packages with Integrated Conductors

EX (QFN)
Terminals: 12
Size: 3 x 3 mm body width



CB
Terminals: 5



LC (SOIC-8)
Terminals: 8



L (SOIC-8 and SOIC-16)
Terminals: 8, 16



LF (QSOP-24)
Terminals: 24



LA / MA (SOIC-16)
Terminals: 16



LR (PSOF)
Terminals: 7



Please Note: Package sizes are photographed to show relative scale.